

LOCTITE[®] ABLESTIK QMI505MT

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PRODUCT DESCRIPTION

 ${\sf LOCTITE} \ensuremath{\$} \ensuremath{\mathsf{ABLESTIK}}$ QMI505MT provides the following product characteristics:

Technology	Rubberized epoxy
Appearance	Silver
Filler type	Silver
Product benefits	 Electrically conductive Hydrophobic Stable at high temperatures Void-free bondline Excellent interfacial adhesion strength Low modulus Reduces inter-package stress
Cure	<i>Skip-</i> Cure process Oven cure
Application	Die attach
Substrates	SBGA™, QFN and TQFP
Surface finishes	Gold, Silver, Ceramics, Palladium and Alloy 42

LOCTITE® ABLESTIK QMI505MT die attach paste is designed for attachment of integrated circuits and components to advanced metal and ceramic surfaces. A package or device manufactured with LOCTITE® ABLESTIK QMI505MT will have good resistance to delamination and "popcorning" after exposure to reflow temperatures.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity @ 25°C, mPa·s (cP)

Speed 5 rpm	12,000
Thixotropic index, (0.5/5 rpm)	4.8
Specific gravity @ 25°C	3.42
Pot life @ 25°C, hours	48
Shelf life @ -40°C, months	12
Flash point - see SDS	

TYPICAL CURING PERFORMANCE

Skip-Cure process using die bonder or wire bonder ≥10 seconds @ 200°C at bondline

Alternative cure schedule using conventional oven

15 minutes @ 185°C (may be suitable to QFN applications) 15 minutes @ 200 to 220°C (for higher adhesion)

Weight loss on cure

By TGA, %

Cure 15 minutes @ 185°C

0.79

The above cure profiles are guideline recommendations. These conditions (time and temperature) may vary based on customers' experience and specific application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical properties

Coefficient of thermal expansion, ppm/°C:

72
170
-10
2.4
≤20
≤20
≤20
≤20
≤0.2
860

Electrical properties

Volume resistivity, ohms-cm ≤0.002

TYPICAL PERFORMANCE OF CURED MATERIAL

Die shear strength, @ 25°C, kg-f: 7.5x7.5 mm, 1 mil BLT, Si die on Ag plated Cu LF 35

GENERAL INFORMATION

Please consult the Safety Data Sheet (SDS) for safe handling information of this product.

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials.

Dispensing

Since thinner bondlines increase stress and may affect adhesion, please call your Henkel Electronics technical service engineer for consultation in cases where bondlines less than 0.0254 mm are desired.



LOCTITE® ABLESTIK QMI505MT as excellent rheology and flows easily under shear stresses such as those present during die bonding. Therefore, bondforces used with other adhesives, which produce a certain bondline thickness, may result in thinner bondlines with LOCTITE® ABLESTIK QMI505MT. Optimization of diebonding parameters is strongly recommended to consistently meet target bondline thicknesses.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal storage: -40°C. Storage below -40°C or above -40°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Henkel representative.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on the specifications of this product.

Conversions

 $(^{\circ}C \times 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches μ m / 25.4 = mil N x 0.225 = lb N/mm x 5.71 = lb/in N/mm² x 145 = psi MPa x 145 = psi N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

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